SISPAD 2026

KUMAMOTO, JAPAN

Second Call for Papers

2026 International Conference on Simulation of Semiconductor Processes and Devices

SISPAD2026

September 28 – 30, 2026
(Workshop: September 27)
Kumamoto-jo Hall, Kumamoto, JAPAN

Sponsored by The Japan Society of Applied Physics
Technical Co-sponsored by The IEEE Electron Devices Society

Scope:

This conference provides an opportunity for the presentation and discussion of the latest advances in modeling and simulation of semiconductor devices and processes.

Topics:

- Modeling and simulation of established semiconductor devices, including FinFETs, GAA FETs, ultra-thin SOI devices, TFTs, optoelectronic devices, memories, sensors, power electronic devices, and organic electronic devices
- Modeling and simulation of emerging devices including tunnel FETs, SETs, spintronic devices, straintronic devices, bio-electronic devices, cryogenic CMOS, emerging memories, neuromorphic devices, quantum computing devices, and new material-based devices for various applications
- Modeling and simulation of all sorts of semiconductor processes, including first-principles material design and growth simulation of nano-scale fabrication
- Fundamental aspects of device modeling and simulation, including quantum transport, thermal transport, fluctuation, noise, and reliability
- Compact modeling for circuit simulation, including low-power, high-frequency, and power electronics applications
- Process/device/circuit co-simulation in the context of system design and verification, including for emerging devices
- Modeling and simulation of interconnects, including noise, parasitic effects, and applications for advanced packaging schemes
- Modeling and simulation of equipment, topography, and lithography
- Numerical methods and algorithms, including grid generation, user interface, and visualization
- Enhancement of simulation methodologies, including multi-physics simulation, multi-scale approaches, and the use of artificial intelligence and quantum computing

Abstract Submission:

Authors are invited to submit a two-page abstract (A4 or US Letter) including figures. Full submission information will be updated in the Second Call for Papers and the following website:

https://sispad2026.jp/ (QR code on the right)

Deadline for submission of abstracts: April 22, 2026
(Extended)

Authors of accepted papers will be required to submit a camera-ready four-page manuscript for inclusion in the Conference Proceedings.

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